

Product Change Notification

(Notification - P1909045-DIGI) (CST-R2-AJ129/130 / DCY001)

September 3, 2019

To: Our Valued Digi-Key Electronics Customer

Overview:

The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification updates certain dates of PCN P1808047 (issued in August 2018) which announced the change in assembly site and materials for select SRAM products. There is a part number change. There is no change to electrical specifications or product reliability.

One or more of following items will change (please see the Appendix for specific details).

- 1. Assembly site from Renesas Semiconductor (Beijing, China) to Greatek Electronics Inc. (Taiwan)
- 2. Base Metal of Lead Frame from 42Alloy to Cu
- 3. Lead Plating from Sn-Cu to Cu
- 4. Die thickness
- 5. Magazine (Tube) specification, or Tape and Reel specification
- 6. Inner lead pattern
- 7. Moisture Sensitivity Level from MSL2 to MSL3
- 8. Topmark specification
- 9. Molding compound to halogen free
- 10. Die bonding from epoxy film to epoxy paste

Affected Products:

A review of our records indicates the products listed in Appendix 1 may affect your company.

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Final last time buy (LTB) orders placed to REA or to a	June 15th, 2019
franchised REA distributor.	June 15 th , 2020
Diagnod data for last time shipment (LTC) from DEA	Dec. 15 th , 2019
Planned date for last time shipment (LTS) from REA.	Dec. 15 th , 2020
Deple coment parts comples	Mar. 2019
Replacement parts samples	Dec. 2019
Deple coment parts made production	June 2019
Replacement parts mass production	Mar. 2020

Response:

Please place last time buy (LTB) orders in a timely manner prior to the key dates listed to avoid product availability issues. If you anticipate volumes beyond your regular rate, please contact your REA sales representative with a forecast of your requirements. Shipments between the LTB and LTS dates are Non-Cancelable and Non-Returnable (NCNR).

Please work with your REA sales representative and/or FAE to transition to the replacement devices.

Please contact your REA sales representative for any questions or comments. Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

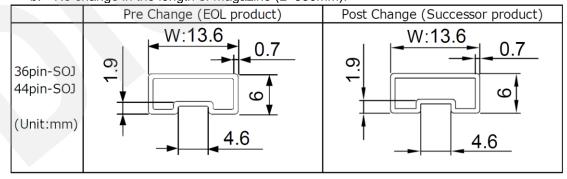


Appendix 1: Affected Part Numbers and Replacements for Digi-Key

Booking Part Number	Replacement PN
R1RP0408DGE-2LR#B0	R1RP0408DGE-2LR#B1
R1RP0408DGE-2PI#B0	R1RP0408DGE-2PI#B1
R1RP0408DGE-2PR#B0	R1RP0408DGE-2PR#B1
R1RP0416DGE-2LR#B0	R1RP0416DGE-2LR#B1
R1RP0416DGE-2PI#B0	R1RP0416DGE-2PI#B1
R1RP0416DGE-2PR#B0	R1RP0416DGE-2PR#B1
R1RW0408DGE-2LR#B0	R1RW0408DGE-2LR#B1
R1RW0408DGE-2PI#B0	R1RW0408DGE-2PI#B1
R1RW0408DGE-2PR#B0	R1RW0408DGE-2PR#B1
R1RW0416DGE-2PI#B0	R1RW0416DGE-2PI#B1
R1RW0416DGE-2PR#B0	R1RW0416DGE-2PR#B1

Appendix 2: Magazine (Tube) Specification Change

- a. The cross-sectional shape of magazine is to be changed (see below).
- b. No change in the length of magazine (L=550mm).





Appendix 3: Change Details [36pin-SOJ 4Mb Fast(5V) x8, Part Name: R1RP0408DGE-***]

Item		Pre change (EOL product)	Post change (Successor product)	
Orderable	part name	R1RP0408DGE-2LR/-2PI/-2PR#B0 (Magazine packing)	R1RP0408DGE-2LR/-2PI/-2PR#B1 (Magazine packing)	
Assembly	line	Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)	
Country of	f origin display	CHINA	TAIWAN	
JEITA Pack	kage Code	P-SOJ36-10.16x23.39-1.27	←	
Package m specificatio (The Electi characteris example.)	on rical	R1RP0408DGE CHINA 2PI XXXXXXXX R1RP0408DGE Part name Electrical characteristics XXXXXXXX Date code Index mark Country of origin (Back-End Line: Assembly)	R1RP0408DGE TAIWAN 2PI O XXXXXXXXX UUUUUUUUUUUUUUUUUUUUUUUUUU	
Assembly Material	Lead frame material	42Alloy	Cu	
	Inner lead pattern	Current pattern	Changed	
	Outer lead pattern	Current pattern	Unchanged	
	Lead plating	Sn-Cu	Sn (pure tin)	
	Die bonding	Epoxy film	Epoxy paste	
	Wire bonding	Au	Au	
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)	
Die thickne	ess	Current thickness	Changed	
Final test I	ine	Powertech Technology Inc. (Taiwan)	←	
Magazine packing	Magazine	Magagine code : JP400PC	New specification	
	Storage number	22pcs/magazine	←	
	Number of magazines (Max.)	60 magazines	←	
	Inner box size (LxWxH)	595mm x 170mm x 72mm	-	
Moisture-p performan		MSL 2	MSL 3	
Shipping la	abel	Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)	



Appendix 4: Change Details [36pin-SOJ 4Mb Fast(3V) x8, Part Name: R1RW0408DGE-***]

Item		Pre change (EOL product)	Post change (Successor product)
Orderable	part name	R1RW0408DGE-2LR/-2PI/-2PR#B0 (Magazine packing)	R1RW0408DGE-2LR/-2PI/-2PR#B1 (Magazine packing)
Assembly	line	Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)
Country o	f origin display	CHINA	TAIWAN
JEITA Pack	kage Code	P-SOJ36-10.16x23.39-1.27	←
Package n specificatio (The Elect characteris example.)	on rical stics is an	R1RW0408DGE CHINA 2PI O XXXXXXXX DUDUUUUUUUUUUUUUUUUUUUUUUUUU	R1RW0408DGE TAIWAN 2PI OXXXXXXXX DUDUUUUUUUUUUUUUUUUUUUUUUUUUU
Assembly Material	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickn	ess	Current thickness	Changed
Final test I	ine	Powertech Technology Inc. (Taiwan)	←
Magazine packing	Magazine	Magagine code : JP400PC	New specification
	Storage number	22pcs/magazine	←
	Number of magazines (Max.)	60 magazines	←
	Inner box size (LxWxH)	595mm x 170mm x 72mm	←
Moisture-p performar		MSL 2	MSL 3
Shipping la	abel	Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)



Appendix 5: Change Details [44pin-SOJ 4Mb Fast(5V) x16, Part Name: R1RP0416DGE-***]

Item		Pre change (EOL product)	Post change (Successor product)
Orderable	part name	R1RP0416DGE -2LR/-2PI/-2PR/-2SR/-2UR/-2VR#B0 (Magazine packing) -2LR/-2PR#BN (Magazine packing)	R1RP0416DGE -2LR/-2PI/-2PR/-2SR/-2UR/-2VR#B1 (Magazine packing)
Assembly	line	Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)
Country o	f origin display	CHINA	TAIWAN
JEITA Pac	kage Code	P-SOJ44-10.16x28.47-1.27	←
Package n specificatio (The Elect characteri example.)	on rical stics is an	R1RP0416DGE CHINA 2PI XXXXXXXX DDDDDDDDDDDDDDDDDDDDDDDDDD	R1RP0416DGE TAIWAN 2PI O XXXXXXXXX UUUUUUUUUUUUUUUUUUUUUUUUUU
	Lead frame material	42Alloy	Cu
	Inner lead pattern	Current pattern	Changed
Assembly Material	Outer lead pattern	Current pattern	Unchanged
	Lead plating	Sn-Cu	Sn (pure tin)
	Die bonding	Epoxy film	Epoxy paste
	Wire bonding	Au	Au
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)
Die thickn	ess	Current thickness	Changed
Final test l	line	Powertech Technology Inc. (Taiwan)	←
Magazine packing	Magazine	Magagine code : JP400PC	New specification
	Storage number	18pcs/magazine	←
	Number of magazines (Max.)	60 magazines	←
	Inner box size (LxWxH)	595mm x 170mm x 72mm	←
Moisture-p performar		MSL 2	MSL 3
Shipping I	abel	Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)



Appendix 6: Change Details [44pin-SOJ 4Mb Fast(3V) x16 Part name: R1RW0416DGE-***]

Item		Pre change (EOL product)	Post change (Successor product)	
Orderable	part name	R1RW0416DGE-2LR/-2PI/-2PR#B0 (Magazine packing)	R1RW0416DGE-2LR/-2PI/-2PR#B1 (Magazine packing)	
Assembly	line	Renesas Semiconductor Beijing (China)	Greatek Electronics Inc. (Taiwan)	
Country o	f origin display	CHINA	TAIWAN	
JEITA Pac	kage Code	P-SOJ44-10.16x28.47-1.27	←	
Package n specificati (The Elect characteri example.)	on :rical stics is an	R1RW0416DGE CHINA 2PI OXXXXXXXX DUDUUUUUUUUUUUUUUUUUUUUUUUUU	R1RW0416DGE TAIWAN 2PI XXXXXXXXX DUDUUUUUUUUUUUUUUUUUUUUUUU	
Assembly Material	Lead frame material	42Alloy	Cu	
	Inner lead pattern	Current pattern	Changed	
	Outer lead pattern	Current pattern	Unchanged	
riacciiai	Lead plating	Sn-Cu	Sn (pure tin)	
	Die bonding	Epoxy film	Epoxy paste	
	Wire bonding	Au	Au	
	Mold	Epoxy resin (Halogen-included)	Epoxy resin (Halogen-free)	
Die thickn	ess	Current thickness	Changed	
Final test	line	Powertech Technology Inc. (Taiwan)	←	
Magazine packing	Magazine	Magagine code : JP400PC	New specification	
	Storage number	18pcs/magazine	←	
	Number of magazines (Max.)	60 magazines	←	
	Inner box size (LxWxH)	595mm x 170mm x 72mm	←	
Moisture- performar		MSL 2	MSL 3	
Shipping I	abel	Current specification	No change in format (Changes in orderable part name, country of origin and MSL display)	